

**AMENDMENTS TO THE CLAIMS:**

***Claims 1-20 (cancelled)***

21. (Currently Amended) A module comprising:

a substrate having ~~a lateral side~~, an upper side, ~~and a lower side~~, and a lateral side that defines a surface;

a recess in said lateral side; and

an electrode in said recess and spaced from said lateral side such that no portion of said electrode is co-planar with said surface.

22. (Previously Presented) The module according to claim 21, further comprising:

an electronic component mounted on said substrate.

23. (Previously Presented) The module according to claim 22, further comprising:

a land, on said upper side, adjacent said recess and connected to said electrode; and

a land, on said lower side, adjacent said recess and connected to said electrode.

24. (Currently Amended) The module according to claim 22, wherein

said substrate comprises a multi-layer substrate that includes a land adjacent said electrode, and an internal layer having thereon an internal a pattern and a land adjacent said electrode, with said land being connected to said ~~internal~~ pattern and said electrode.

25. (Previously Presented) The module according to claim 22, further comprising:

another electrode at said lateral side.

26. (Previously Presented) The module according to claim 22, wherein said substrate has a corner, and further comprising:

another electrode at said corner.

27. (Currently Amended) The module according to claim 22, wherein said recess ~~is formed from~~ comprises plural recesses that extend from said upper side to said lower side.

28. (Previously Presented) The module according to claim 27, further comprising:  
a metal shield case covering said electronic component, said metal shield case having a leg joined to said electrode.

29. (Previously Presented) The module according to claim 28, wherein said lateral side is positioned outwardly beyond said metal shield case.

30. (Previously Presented) The module according to claim 28, wherein said metal shield case has a lateral side, with said lateral side of said substrate being substantially flush and parallel with said lateral side of said metal shield case.

31. (Previously Presented) The module according to claim 28, wherein said metal shield case has a lateral side and an upper side, with said lateral side of said metal shield case being more textured than said upper side of said metal shield case.

32. (Previously Presented) The module according to claim 28, wherein said leg is soldered to said electrode.

***Claim 33 (Cancelled)***

34. (Previously Presented) A method comprising:  
forming a hole in a mother board from which substrates are to be provided by cutting said mother board;

forming a metal plated portion on said mother board around said hole and on an interior surface of said hole;

covering said metal plated portion with a resist;

curing said resist;

placing a mask over said resist so as to expose regions of said resist, which regions include portions of said resist that are positioned over part of said metal plated portion on said interior surface of said hole;

subjecting the exposed regions of said resist to light so as to decompose said exposed regions of said resist;

removing the decomposed exposed regions of said resist so as to expose the part of said metal plated portion on said interior surface of said hole over which the exposed portions of said resist were positioned; and

removing the exposed part of said metal plated portion from said interior surface of said hole.

35. (Previously Presented) The method according to claim 34, further comprising:

cutting said mother board through portions of said interior surface of said hole from which said exposed part of said metal plated portion was removed.

36. (Previously Presented) The method according to claim 34, wherein

forming a hole in a mother board comprises forming a hole at a location that is to correspond to a corner of a substrate to be provided by cutting said mother board.

37. (Previously Presented) The method according to claim 34, wherein

forming a hole in a mother board comprises forming a slot in said mother board by consecutively drilling round holes.

38. (Previously Presented) The method according to claim 37, wherein

consecutively drilling round holes comprises first drilling a first hole, then drilling a second hole, and then drilling a third hole, with said third hole being positioned between said first and second holes.

39. (Previously Presented) A method comprising:

forming a hole in a mother board from which substrates are to be provided by cutting said mother board;

forming a metal plated portion on said mother board around said hole and on an interior surface of said hole;

covering said metal plated portion with a resist;

placing a mask over said resist so as to expose regions of said resist while covering other regions of said resist, which other regions include portions of said resist that are positioned over part of said metal plated portion on said interior surface of said hole;

subjecting the exposed regions of said resist to light so as to cure said exposed regions of said resist while leaving the covered regions of said resist uncured;

removing the uncured regions of said resist so as to expose the part of said metal plated portion on said interior surface of said hole over which the covered portions of said resist were positioned; and

removing the exposed part of said metal plated portion from said interior surface of said hole.

40. (Previously Presented) The method according to claim 39, further comprising:

cutting said mother board through portions of said interior surface of said hole from which said exposed part of said metal plated portion was removed.

41. (Previously Presented) The method according to claim 39, wherein

forming a hole in a mother board comprises forming a hole at a location that is to correspond to a location where four adjacent substrates are to meet upon cutting said mother board.

42. (Previously Presented) The method according to claim 39, wherein

forming a hole in a mother board comprises forming a slot in said mother board by consecutively drilling round holes.

43. (Previously Presented) The method according to claim 42, wherein consecutively drilling round holes comprises first drilling a first hole, then drilling a second hole, and then drilling a third hole, with said third hole being positioned between said first and second holes.